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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	CANbus, I²C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	64
Program Memory Size	60KB (60K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st72f521m9t6tr

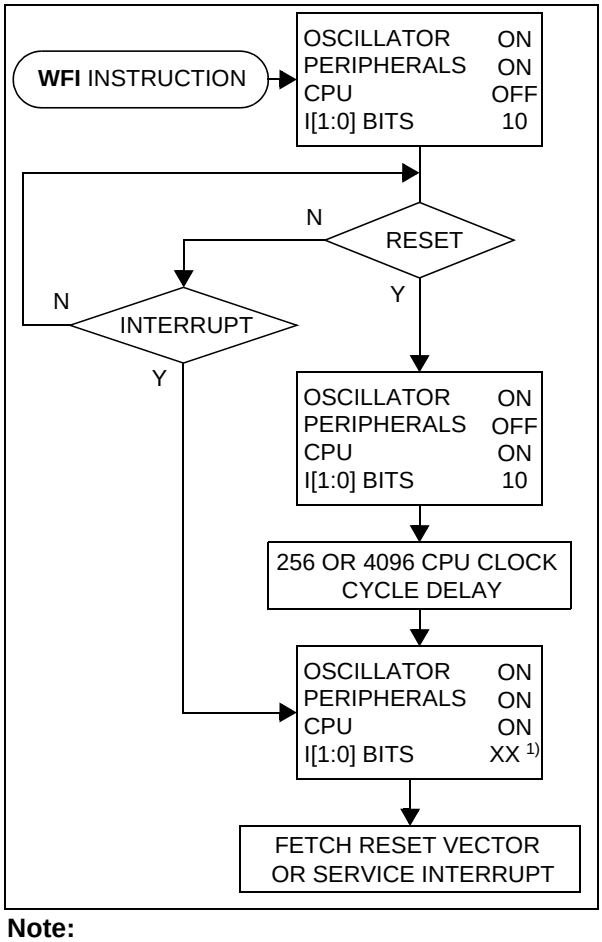
POWER SAVING MODES (Cont'd)

8.3 WAIT MODE

WAIT mode places the MCU in a low power consumption mode by stopping the CPU.
This power saving mode is selected by calling the 'WFI' instruction.
All peripherals remain active. During WAIT mode, the I[1:0] bits of the CC register are forced to '10', to enable all interrupts. All other registers and memory remain unchanged. The MCU remains in WAIT mode until an interrupt or RESET occurs, whereupon the Program Counter branches to the starting address of the interrupt or Reset service routine.
The MCU will remain in WAIT mode until a Reset or an Interrupt occurs, causing it to wake up.

Refer to Figure 25.

Figure 25. WAIT Mode Flow-chart



Note:

1. Before servicing an interrupt, the CC register is pushed on the stack. The I[1:0] bits of the CC register are set to the current software priority level of the interrupt routine and recovered when the CC register is popped.

POWER SAVING MODES (Cont'd)

8.4.2 HALT MODE

The HALT mode is the lowest power consumption mode of the MCU. It is entered by executing the 'HALT' instruction when the OIE bit of the Main Clock Controller Status register (MCCSR) is cleared (see section 10.2 on page 58 for more details on the MCCSR register).

The MCU can exit HALT mode on reception of either a specific interrupt (see Table 7, "Interrupt Mapping," on page 38) or a RESET. When exiting HALT mode by means of a RESET or an interrupt, the oscillator is immediately turned on and the 256 or 4096 CPU cycle delay is used to stabilize the oscillator. After the start up delay, the CPU resumes operation by servicing the interrupt or by fetching the reset vector which woke it up (see Figure 29).

When entering HALT mode, the I[1:0] bits in the CC register are forced to '10b'to enable interrupts. Therefore, if an interrupt is pending, the MCU wakes up immediately.

In HALT mode, the main oscillator is turned off causing all internal processing to be stopped, including the operation of the on-chip peripherals. All peripherals are not clocked except the ones which get their clock supply from another clock generator (such as an external or auxiliary oscillator).

The compatibility of Watchdog operation with HALT mode is configured by the "WDGHALT" option bit of the option byte. The HALT instruction when executed while the Watchdog system is enabled, can generate a Watchdog RESET (see section 14.1 on page 201 for more details).

Figure 28. HALT Timing Overview

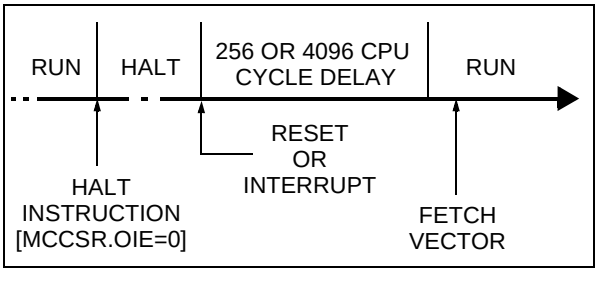
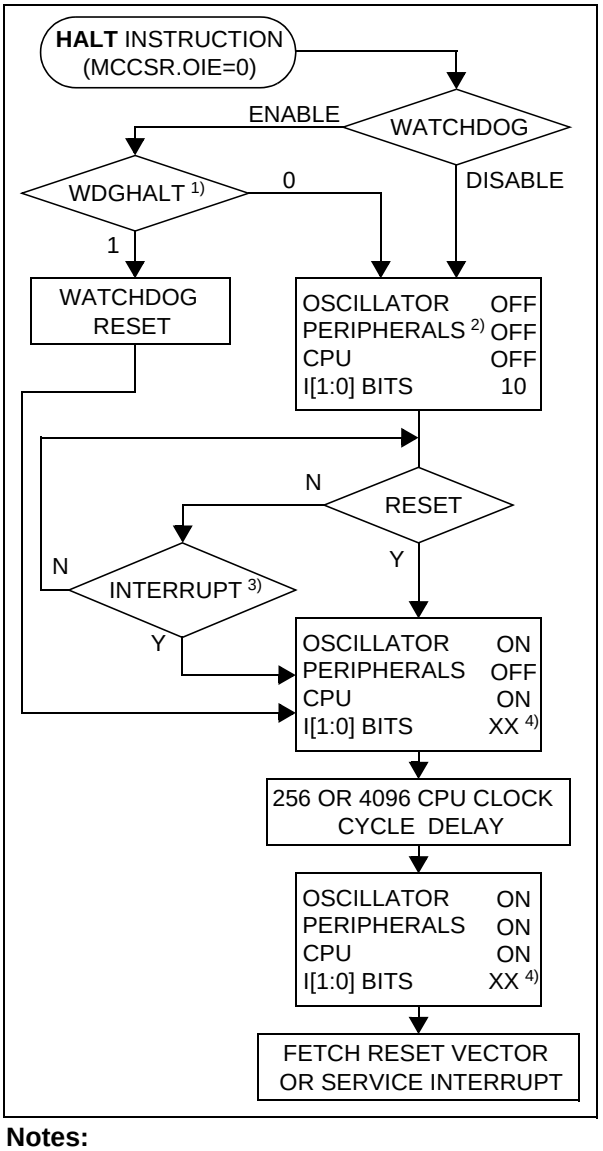


Figure 29. HALT Mode Flow-chart



Notes:

1. WDGHALT is an option bit. See option byte section for more details.
2. Peripheral clocked with an external clock source can still be active.
3. Only some specific interrupts can exit the MCU from HALT mode (such as external interrupt). Refer to Table 7, "Interrupt Mapping," on page 38 for more details.
4. Before servicing an interrupt, the CC register is pushed on the stack. The I[1:0] bits of the CC register are set to the current software priority level of the interrupt routine and recovered when the CC register is popped.

I/O PORTS (Cont'd)

Table 12. I/O Port Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
Reset Value of all I/O port registers		0	0	0	0	0	0	0	0
0000h	**PADR**	MSB							LSB
0001h	**PADDR**								
0002h	**PAOR**								
0003h	**PBDR**	MSB							LSB
0004h	**PBDDR**								
0005h	**PBOR**								
0006h	**PCDR**	MSB							LSB
0007h	**PCDDR**								
0008h	**PCOR**								
0009h	**PDDR**	MSB							LSB
000Ah	**PDDDR**								
000Bh	**PDOR**								
000Ch	**PEDR**	MSB							LSB
000Dh	**PEDDR**								
000Eh	**PEOR**								
000Fh	**PFDR**	MSB							LSB
0010h	**PFDDR**								
0011h	**PFOR**								
0012h	**PGDR**	MSB							LSB
0013h	**PGDDR**								
0014h	**PGOR**								
0015h	**PHDR**	MSB							LSB
0016h	**PHDDR**								
0017h	**PHOR**								

Related Documentation

AN 970: SPI Communication between ST7 and EEPROM

AN1045: S/W implementation of I2C bus master

AN1048: Software LCD driver

Table 13. Watchdog Timer Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
002Ah	**WDGCR**	WDGA	T6	T5	T4	T3	T2	T1	T0
	Reset Value	0	1	1	1	1	1	1	1

10.3 PWM AUTO-RELOAD TIMER (ART)

10.3.1 Introduction

The Pulse Width Modulated Auto-Reload Timer on-chip peripheral consists of an 8-bit auto reload counter with compare/capture capabilities and of a 7-bit prescaler clock source.

These resources allow five possible operating modes:

– Generation of up to 4 independent PWM signals

– Output compare and Time base interrupt

– Up to two input capture functions

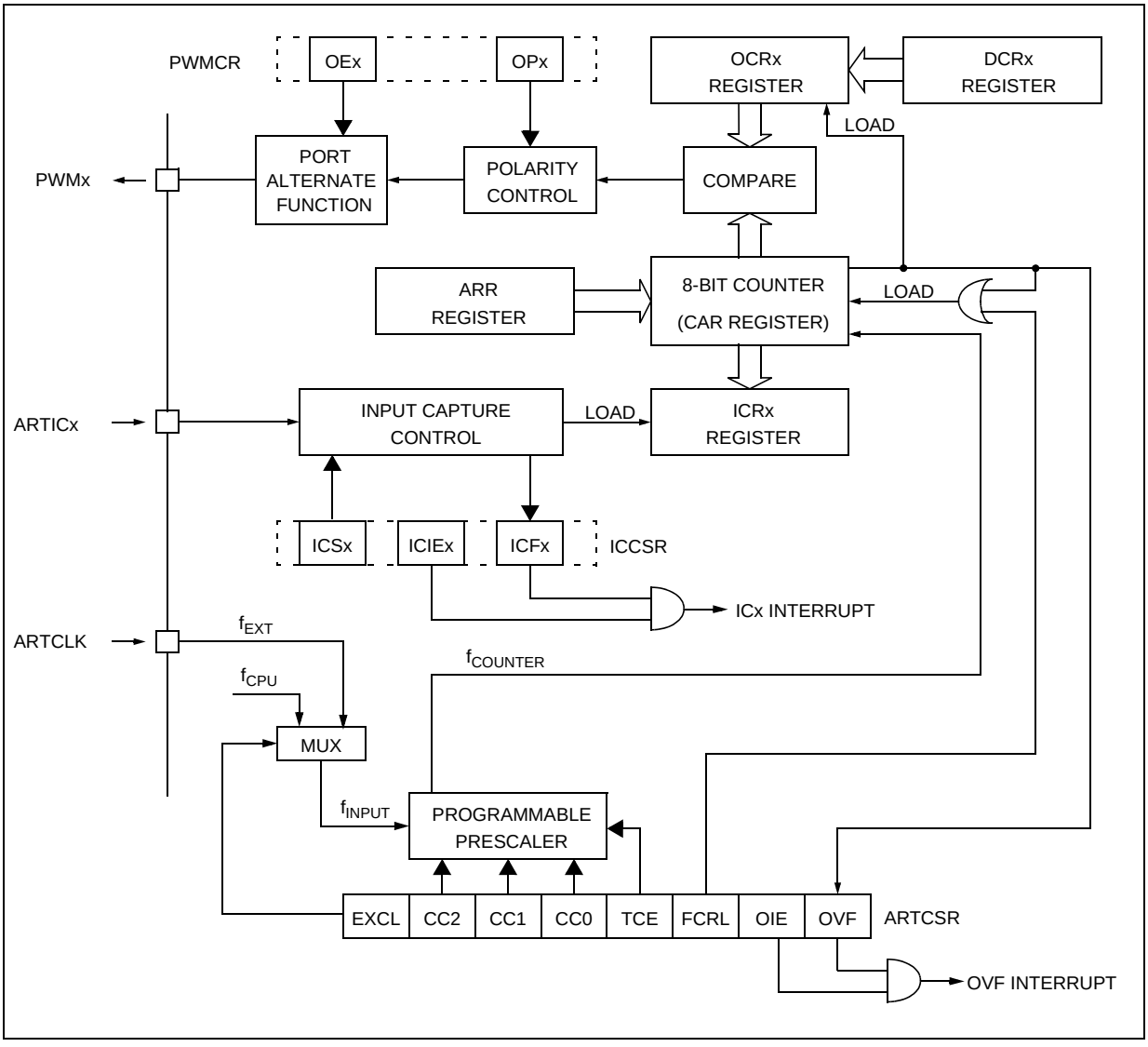
– External event detector

– Up to two external interrupt sources

The three first modes can be used together with a single counter frequency.

The timer can be used to wake up the MCU from WAIT and HALT modes.

Figure 36. PWM Auto-Reload Timer Block Diagram



PWM AUTO-RELOAD TIMER (Cont'd)

Independent PWM signal generation

This mode allows up to four Pulse Width Modulated signals to be generated on the PWMx output pins with minimum core processing overhead. This function is stopped during HALT mode.

Each PWMx output signal can be selected independently using the corresponding OEx bit in the PWM Control register (PWMCR). When this bit is set, the corresponding I/O pin is configured as output push-pull alternate function.

The PWM signals all have the same frequency which is controlled by the counter period and the ARTARR register value.

$$f_{PWM} = f_{COUNTER} / (256 - ARTARR)$$

When a counter overflow occurs, the PWMx pin level is changed depending on the corresponding OPx (output polarity) bit in the PWMCR register. When the counter reaches the value contained in one of the output compare register (OCRx) the corresponding PWMx pin level is restored.

It should be noted that the reload values will also affect the value and the resolution of the duty cycle of the PWM output signal. To obtain a signal on a PWMx pin, the contents of the OCRx register must be greater than the contents of the ARTARR register.

The maximum available resolution for the PWMx duty cycle is:

$$Resolution = 1 / (256 - ARTARR)$$

Note: To get the maximum resolution (1/256), the ARTARR register must be 0. With this maximum resolution, 0% and 100% can be obtained by changing the polarity.

Figure 38. PWM Auto-reload Timer Function

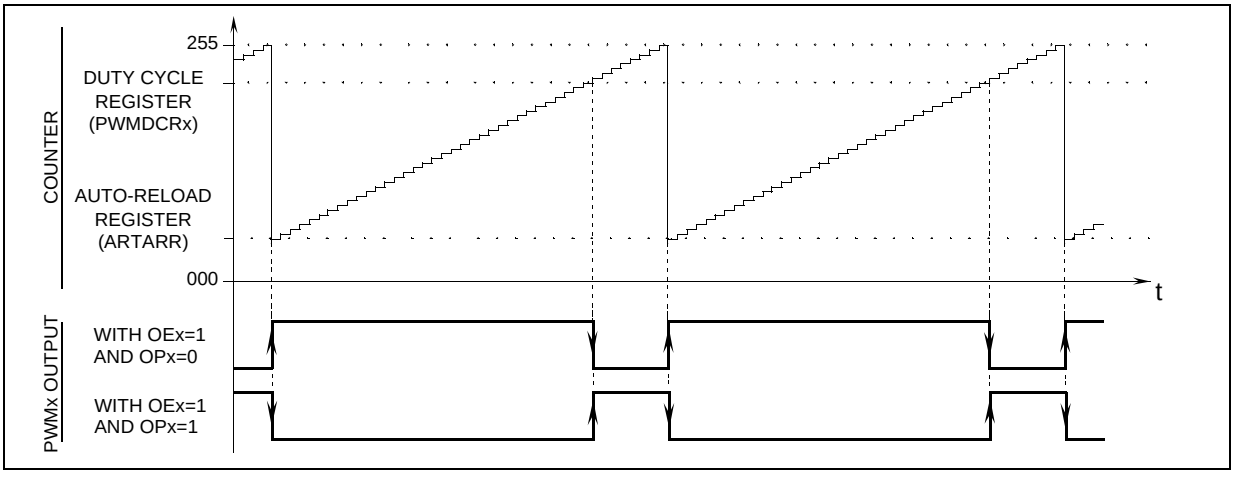
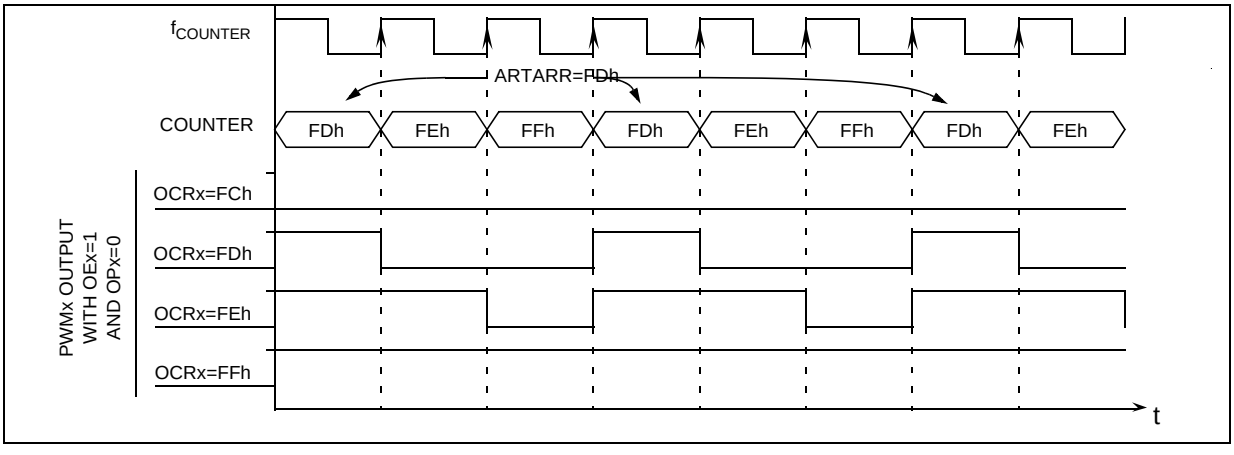


Figure 39. PWM Signal from 0% to 100% Duty Cycle



16-BIT TIMER (Cont'd)

10.4.3.4 Output Compare

In this section, the index, *i*, may be 1 or 2 because there are 2 output compare functions in the 16-bit timer.

This function can be used to control an output waveform or indicate when a period of time has elapsed.

When a match is found between the Output Compare register and the free running counter, the output compare function:

- Assigns pins with a programmable value if the OC*i*E bit is set
- Sets a flag in the status register
- Generates an interrupt if enabled

Two 16-bit registers Output Compare Register 1 (OC1R) and Output Compare Register 2 (OC2R) contain the value to be compared to the counter register each timer clock cycle.

	MS Byte	LS Byte
OC*i*R	OC*i*HR	OC*i*LR

These registers are readable and writable and are not affected by the timer hardware. A reset event changes the OC*i*R value to 8000h.

Timing resolution is one count of the free running counter: ($f_{CPU/CC[1:0]}$).

Procedure:

To use the output compare function, select the following in the CR2 register:

- Set the OC*i*E bit if an output is needed then the OCMP*i* pin is dedicated to the output compare *i* signal.
- Select the timer clock (CC[1:0]) (see Table 16 Clock Control Bits).

And select the following in the CR1 register:

- Select the OLVL*i* bit to applied to the OCMP*i* pins after the match occurs.
- Set the OCIE bit to generate an interrupt if it is needed.

When a match is found between OCRi register and CR register:

- OCF*i* bit is set.
- The OCMP*i* pin takes OLVL*i* bit value (OCMP*i* pin latch is forced low during reset).
- A timer interrupt is generated if the OCIE bit is set in the CR1 register and the I bit is cleared in the CC register (CC).

The OC*i*R register value required for a specific timing application can be calculated using the following formula:

$$\Delta \text{ OC}i\text{R} = \frac{\Delta t * f_{CPU}}{PRESC}$$

Where:

Δt = Output compare period (in seconds)

f_{CPU} = CPU clock frequency (in hertz)

PRESC = Timer prescaler factor (2, 4 or 8 depending on CC[1:0] bits, see Table 16 Clock Control Bits)

If the timer clock is an external clock, the formula is:

$$\Delta \text{ OC}i\text{R} = \Delta t * f_{EXT}$$

Where:

Δt = Output compare period (in seconds)

f_{EXT} = External timer clock frequency (in hertz)

Clearing the output compare interrupt request (i.e. clearing the OCF*i* bit) is done by:

1. Reading the SR register while the OCF*i* bit is set.
2. An access (read or write) to the OC*i*LR register.

The following procedure is recommended to prevent the OCF*i* bit from being set between the time it is read and the write to the OC*i*R register:

- Write to the OC*i*HR register (further compares are inhibited).
- Read the SR register (first step of the clearance of the OCF*i* bit, which may be already set).
- Write to the OC*i*LR register (enables the output compare function and clears the OCF*i* bit).

10.5 SERIAL PERIPHERAL INTERFACE (SPI)

10.5.1 Introduction

The Serial Peripheral Interface (SPI) allows full-duplex, synchronous, serial communication with external devices. An SPI system may consist of a master and one or more slaves however the SPI interface can not be a master in a multi-master system.

10.5.2 Main Features

- Full duplex synchronous transfers (on 3 lines)
- Simplex synchronous transfers (on 2 lines)
- Master or slave operation
- Six master mode frequencies (f_{CPU}/4 max.)
- f_{CPU}/2 max. slave mode frequency (see note)
- $\overline{SS}$ Management by software or hardware
- Programmable clock polarity and phase
- End of transfer interrupt flag
- Write collision, Master Mode Fault and Overrun flags

Note: In slave mode, continuous transmission is not possible at maximum frequency due to the software overhead for clearing status flags and to initiate the next transmission sequence.

10.5.3 General Description

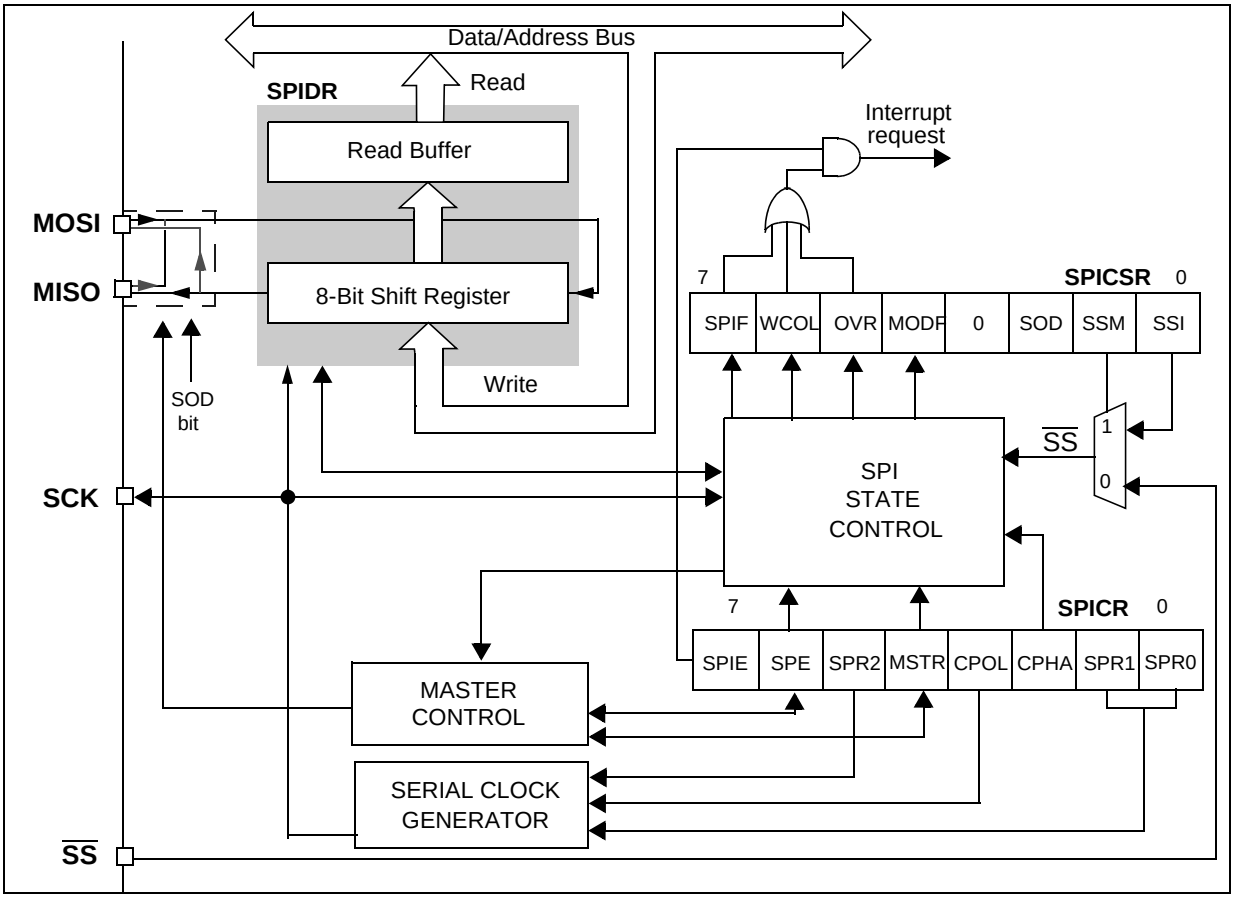
Figure 53 shows the serial peripheral interface (SPI) block diagram. There are 3 registers:

- SPI Control Register (SPICR)
- SPI Control/Status Register (SPICSR)
- SPI Data Register (SPIDR)

The SPI is connected to external devices through 4 pins:

- MISO: Master In / Slave Out data
- MOSI: Master Out / Slave In data
- SCK: Serial Clock out by SPI masters and input by SPI slaves

Figure 53. Serial Peripheral Interface Block Diagram



SERIAL PERIPHERAL INTERFACE (Cont'd)

10.5.3.3 Master Mode Operation

In master mode, the serial clock is output on the SCK pin. The clock frequency, polarity and phase are configured by software (refer to the description of the SPICSR register).

Note: The idle state of SCK must correspond to the polarity selected in the SPICSR register (by pulling up SCK if CPOL=1 or pulling down SCK if CPOL=0).

To operate the SPI in master mode, perform the following steps in order (if the SPICSR register is not written first, the SPICR register setting (MSTR bit) may be not taken into account):

1. Write to the SPICR register:
   - Select the clock frequency by configuring the SPR[2:0] bits.
   - Select the clock polarity and clock phase by configuring the CPOL and CPHA bits. Figure 57 shows the four possible configurations.
     Note: The slave must have the same CPOL and CPHA settings as the master.
2. Write to the SPICSR register:
   - Either set the SSM bit and set the SSI bit or clear the SSM bit and tie the SS pin high for the complete byte transmit sequence.
3. Write to the SPICR register:
   - Set the MSTR and SPE bits
     Note: MSTR and SPE bits remain set only if SS is high).

The transmit sequence begins when software writes a byte in the SPIDR register.

10.5.3.4 Master Mode Transmit Sequence

When software writes to the SPIDR register, the data byte is loaded into the 8-bit shift register and then shifted out serially to the MOSI pin most significant bit first.

When data transfer is complete:

- The SPIF bit is set by hardware
- An interrupt request is generated if the SPIE bit is set and the interrupt mask in the CCR register is cleared.

Clearing the SPIF bit is performed by the following software sequence:

1. An access to the SPICSR register while the SPIF bit is set
2. A read to the SPIDR register.

Note: While the SPIF bit is set, all writes to the SPIDR register are inhibited until the SPICSR register is read.

10.5.3.5 Slave Mode Operation

In slave mode, the serial clock is received on the SCK pin from the master device.

To operate the SPI in slave mode:

1. Write to the SPICSR register to perform the following actions:
   - Select the clock polarity and clock phase by configuring the CPOL and CPHA bits (see Figure 57).
     Note: The slave must have the same CPOL and CPHA settings as the master.
   - Manage the $\overline{SS}$ pin as described in Section 10.5.3.2 and Figure 55. If CPHA=1 $\overline{SS}$ must be held low continuously. If CPHA=0 $\overline{SS}$ must be held low during byte transmission and pulled up between each byte to let the slave write in the shift register.
2. Write to the SPICR register to clear the MSTR bit and set the SPE bit to enable the SPI I/O functions.

10.5.3.6 Slave Mode Transmit Sequence

When software writes to the SPIDR register, the data byte is loaded into the 8-bit shift register and then shifted out serially to the MISO pin most significant bit first.

The transmit sequence begins when the slave device receives the clock signal and the most significant bit of the data on its MOSI pin.

When data transfer is complete:

- The SPIF bit is set by hardware
- An interrupt request is generated if SPIE bit is set and interrupt mask in the CCR register is cleared.

Clearing the SPIF bit is performed by the following software sequence:

1. An access to the SPICSR register while the SPIF bit is set.
2. A write or a read to the SPIDR register.

Notes: While the SPIF bit is set, all writes to the SPIDR register are inhibited until the SPICSR register is read.

The SPIF bit can be cleared during a second transmission; however, it must be cleared before the second SPIF bit in order to prevent an Overrun condition (see Section 10.5.5.2).

SERIAL COMMUNICATIONS INTERFACE (Cont'd)

10.6.4 Functional Description

The block diagram of the Serial Control Interface, is shown in Figure 60. It contains 6 dedicated registers:

– Two control registers (SCICR1 & SCICR2)

– A status register (SCISR)

– A baud rate register (SCIBRR)

– An extended prescaler receiver register (SCIERPR)

– An extended prescaler transmitter register (SCIETPR)

Refer to the register descriptions in Section 10.6.7for the definitions of each bit.

10.6.4.1 Serial Data Format

Word length may be selected as being either 8 or 9 bits by programming the M bit in the SCICR1 register (see Figure 60).

The TDO pin is in low state during the start bit.

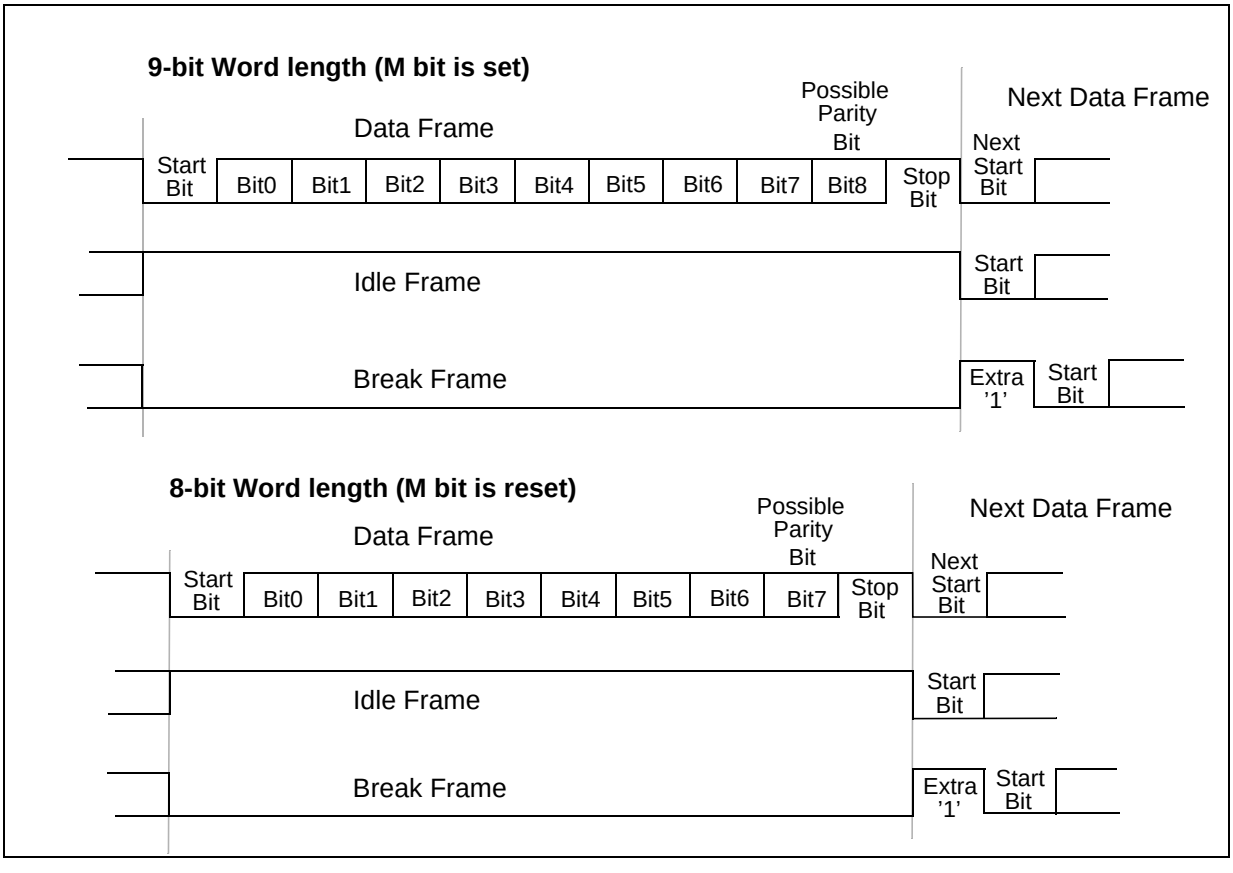
The TDO pin is in high state during the stop bit.

An Idle character is interpreted as an entire frame of "1"s followed by the start bit of the next frame which contains data.

A Break character is interpreted on receiving "0"s for some multiple of the frame period. At the end of the last break frame the transmitter inserts an extra "1" bit to acknowledge the start bit.

Transmission and reception are driven by their own baud rate generator.

Figure 61. Word Length Programming



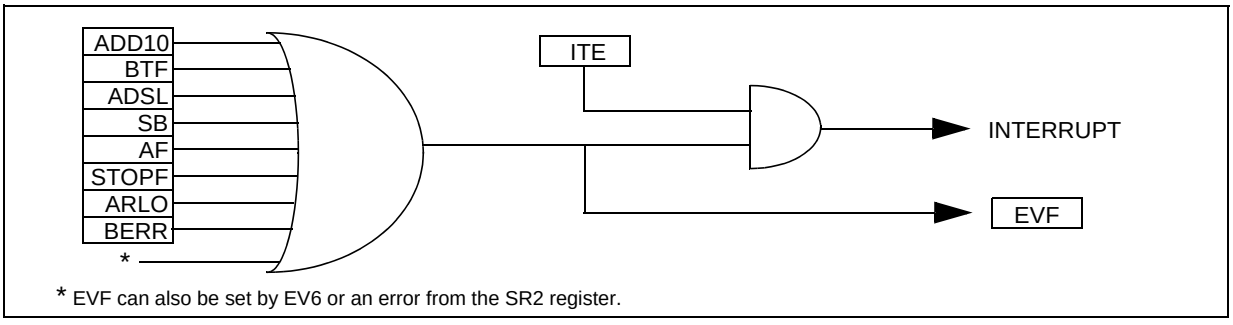
I²C BUS INTERFACE (Cont'd)

10.7.5 Low Power Modes

Mode	Description
WAIT	No effect on I²C interface. I²C interrupts cause the device to exit from WAIT mode.
HALT	I²C registers are frozen. In HALT mode, the I²C interface is inactive and does not acknowledge data on the bus. The I²C interface resumes operation when the MCU is woken up by an interrupt with "exit from HALT mode" capability.

10.7.6 Interrupts

Figure 67. Event Flags and Interrupt Generation



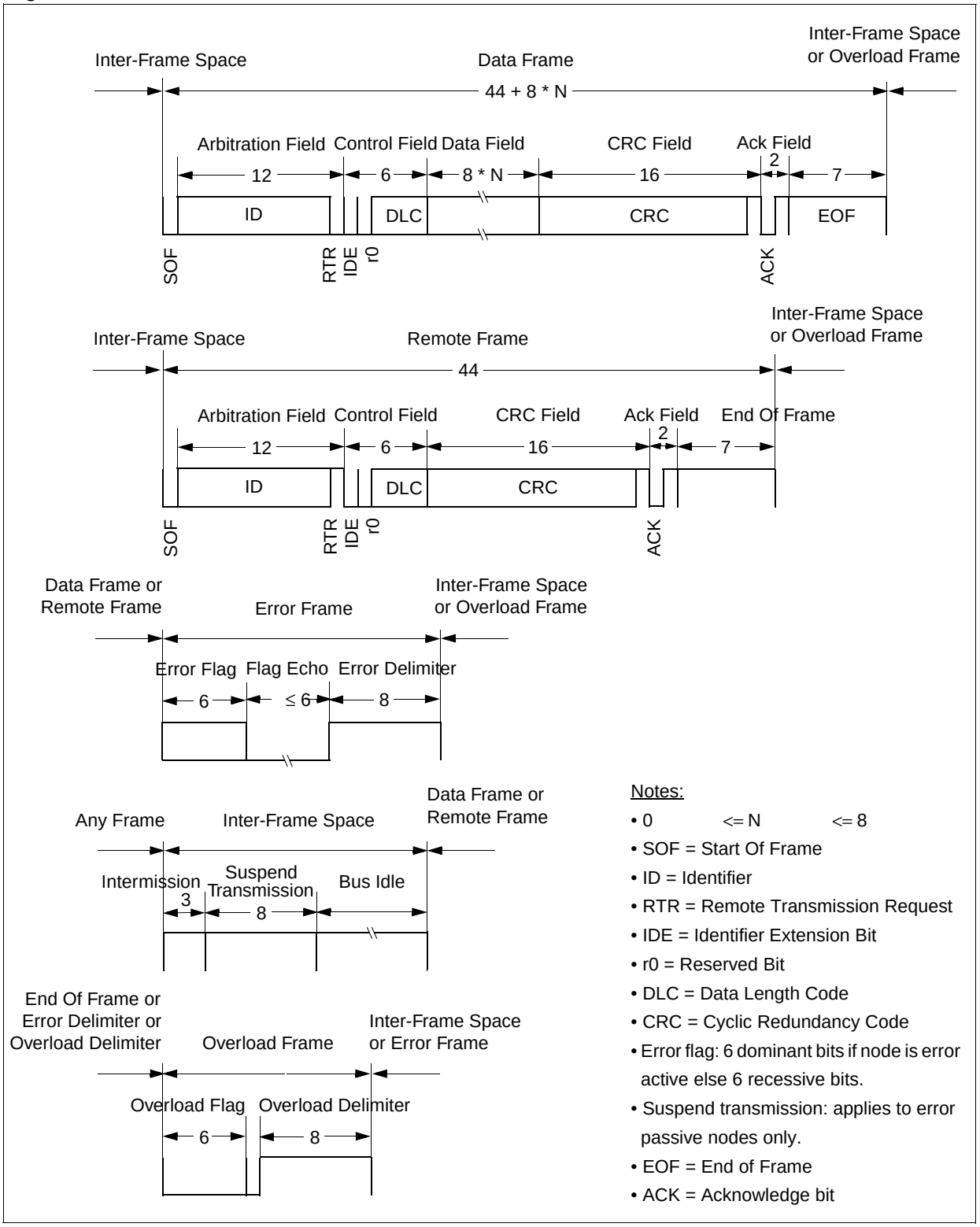
* EVF can also be set by EV6 or an error from the SR2 register.

Interrupt Event	Event Flag	Enable Control Bit	Exit from Wait	Exit from Halt
10-bit Address Sent Event (Master mode)	ADD10	ITE	Yes	No
End of Byte Transfer Event	BTF		Yes	No
Address Matched Event (Slave mode)	ADSEL		Yes	No
Start Bit Generation Event (Master mode)	SB		Yes	No
Acknowledge Failure Event	AF		Yes	No
Stop Detection Event (Slave mode)	STOPF		Yes	No
Arbitration Lost Event (Multimaster configuration)	ARLO		Yes	No
Bus Error Event	BERR		Yes	No

Note: The I²C interrupt events are connected to the same interrupt vector (see Interrupts chapter). They generate an interrupt if the corresponding Enable Control Bit is set and the I-bit in the CC register is reset (RIM instruction).

CONTROLLER AREA NETWORK (Cont'd)

Figure 69. CAN Frames



Notes:

- 0 <= N <= 8
- SOF = Start Of Frame
- ID = Identifier
- RTR = Remote Transmission Request
- IDE = Identifier Extension Bit
- r0 = Reserved Bit
- DLC = Data Length Code
- CRC = Cyclic Redundancy Code
- Error flag: 6 dominant bits if node is error active else 6 recessive bits.
- Suspend transmission: applies to error passive nodes only.
- EOF = End of Frame
- ACK = Acknowledge bit

CONTROLLER AREA NETWORK (Cont'd)

Workaround Description

The bus-off entry works correctly in almost all cases, only when REC is greater than 127 a bus-off will not be recognized by pCAN. Therefore the pCAN bus-off signalling (BOFF) is still used but it needs to be complemented by monitoring TEC by software.

To detect the bus-off condition by software the application has to monitor the value of the TEC register periodically. An overflow signals a bus-off condition. When a bus-off condition has been detected the application must execute the following sequence to recover from bus-off properly: the application stops pCAN by clearing the RUN bit in the CANCSR register resets all pending transmission by clearing the LOCK bit in the BCSR register and starts it again by setting the RUN bit.

To detect the bus-off condition properly, the TEC monitoring period must be lower than the time between two overflows. As the problem only occurs when pCAN is in Error Passive State (REC > 127) pCAN will continuously try to send a SOF followed by an Error Passive Flag and a Suspend Transmission. This leads to 26 (1 + 6 + 8 + 3 + 8) bit times. Each time TEC is incremented by 8, hence to reach 256 the sequence must be executed 32 times. Under these conditions the shortest sequence leading to a TEC overflow lasts 832 bit times.

Depending on the baudrate the application will have to adapt the monitoring period, for example at 500kbps the period must be less than 1600us.

The 'C' code below shows an implementation example of the monitoring sequence. This code is called periodically as described above.

To detect the overflow, the test condition must take into account that TEC might also have been decremented due to a successful transmission. So an overflow condition is detected:

IF the current TEC value is lower than the previous TEC value

AND the difference is greater than the number of possible successful transmissions during the monitoring period.

In the example above, one message can be sent, therefore one is added to CANTECR.

```
*********************************************/
/* INITIALISATION
/*********************************************/
unsigned char TECReg=0; //Previous value of TEC
unsigned char BusOffFlag=0; //Set to one if bus-off

/*********************************************/
/* BUS-OFF MONITORING SEQUENCE
/*********************************************/

if( (CANCSR & BOFF) || ( CANTECR+1 < TECReg) )
{
                    BusOffFlag = 1;
}
else
{
              TECReg = CANTECR;
}
```

CLOCK AND TIMING CHARACTERISTICS (Cont'd)

Supplier	f_{OSC} (MHz)	Typical Ceramic Resonators	
		Reference[2]	Recommended OSCRANGE Option bit configuration
Murata	2	CSTCC2M00G56A-R0	MP Mode[3]
	4	CSTCR4M00G55B-R0	MS Mode
	8	CSTCE8M00G55A-R0	HS Mode
	16	CSTCE16M0G53A-R0	HS Mode

Notes:

1. Resonator characteristics given by the ceramic resonator manufacturer.
2. SMD = [-R0: Plastic tape package (∅ =180mm), -B0: Bulk]
   LEAD = [-A0: Flat pack package (Radial taping Ho= 18mm), -B0: Bulk]
3. LP mode is not recommended for 2 MHz resonator because the peak to peak amplitude is too small (>0.8V)

For more information on these resonators, please consult www.murata.com

12.7 EMC CHARACTERISTICS

Susceptibility tests are performed on a sample basis during product characterization.

12.7.1 Functional EMS (Electro Magnetic Susceptibility)

Based on a simple running application on the product (toggling 2 LEDs through I/O ports), the product is stressed by two electro magnetic events until a failure occurs (indicated by the LEDs).

- **ESD**: Electro-Static Discharge (positive and negative) is applied on all pins of the device until a functional disturbance occurs. This test conforms with the IEC 1000-4-2 standard.
- **FTB**: A Burst of Fast Transient voltage (positive and negative) is applied to V_{DD} and V_{SS} through a 100pF capacitor, until a functional disturbance occurs. This test conforms with the IEC 1000-4-4 standard.

A device reset allows normal operations to be resumed. The test results are given in the table below based on the EMS levels and classes defined in application note AN1709.

12.7.1.1 Designing hardened software to avoid noise problems

EMC characterization and optimization are performed at component level with a typical application environment and simplified MCU software. It should be noted that good EMC performance is highly dependent on the user application and the software in particular.

Therefore it is recommended that the user applies EMC software optimization and prequalification tests in relation with the EMC level requested for his application.

Software recommendations:

The software flowchart must include the management of runaway conditions such as:

– Corrupted program counter

– Unexpected reset

– Critical Data corruption (control registers...)

Prequalification trials:

Most of the common failures (unexpected reset and program counter corruption) can be reproduced by manually forcing a low state on the RESET pin or the Oscillator pins for 1 second.

To complete these trials, ESD stress can be applied directly on the device, over the range of specification values. When unexpected behaviour is detected, the software can be hardened to prevent unrecoverable errors occurring (see application note AN1015)

.

Symbol	Parameter	Conditions	Level/ Class
V_{FESD}	Voltage limits to be applied on any I/O pin to induce a functional disturbance	Flash device: V_{DD}=5V, T_A=+25°C, f_{OSC}=8MHz, conforms to IEC 1000-4-2	4B
		ROM device: V_{DD}=5V, T_A=+25°C, f_{OSC}=8MHz,conforms to IEC 1000-4-2	3B
V_{FFTB}	Fast transient voltage burst limits to be applied through 100pF on V_{DD} and V_{DD} pins to induce a functional disturbance	Flash device: V_{DD}=5V, T_A=+25°C, f_{OSC}=8 MHz, conforms to IEC 1000-4-4	3B
V_{FFTB}	Fast transient voltage burst limits to be applied through 100pF on V_{DD} and V_{DD} pins to induce a functional disturbance	Flash device: V_{DD}=5V, T_A=+25°C, f_{OSC}=8 MHz, conforms to IEC 1000-4-4	3B

CONTROL PIN CHARACTERISTICS (Cont'd)

Figure 103. $\overline{\text{RESET}}$ pin protection when LVD is enabled.[1)2)3)4)]

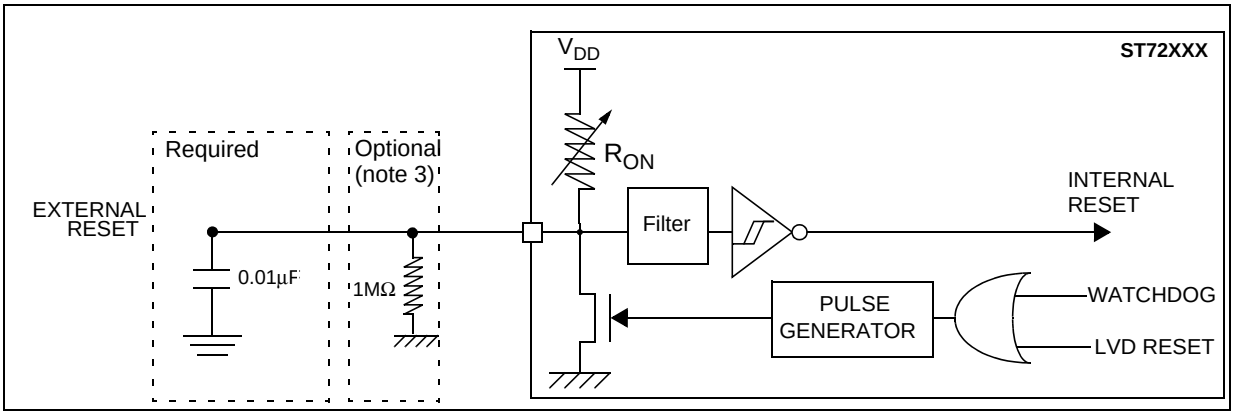
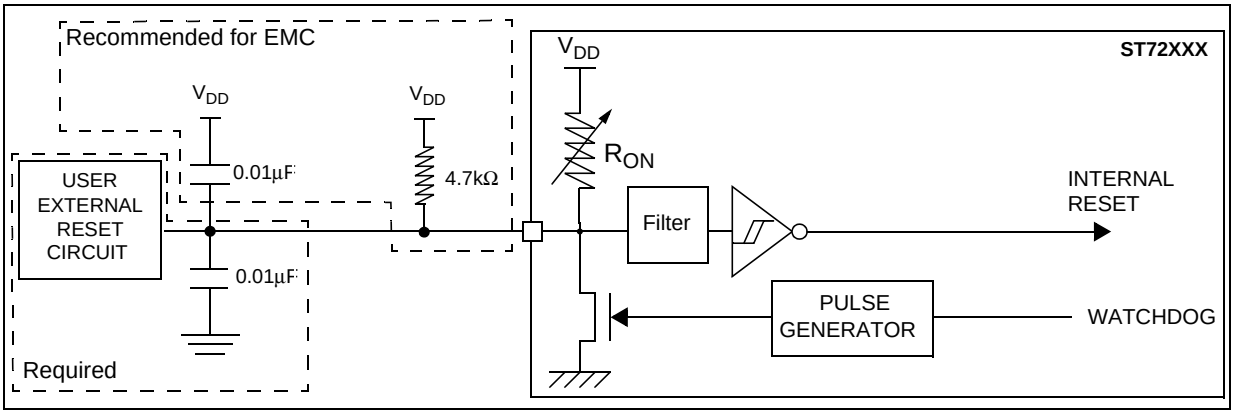


Figure 104. $\overline{\text{RESET}}$ pin protection when LVD is disabled.[1)]



Note 1:

- The reset network protects the device against parasitic resets.
- The output of the external reset circuit must have an open-drain output to drive the ST7 reset pad. Otherwise the device can be damaged when the ST7 generates an internal reset (LVD or watchdog).
- Whatever the reset source is (internal or external), the user must ensure that the level on the $\overline{\text{RESET}}$ pin can go below the V_{IL} max. level specified in section 12.9.1 on page 185. Otherwise the reset will not be taken into account internally.
- Because the reset circuit is designed to allow the internal RESET to be output in the $\overline{\text{RESET}}$ pin, the user must ensure that the current sunk on the $\overline{\text{RESET}}$ pin is less than the absolute maximum value specified for $I_{INJ(RESET)}$ in section 12.2.2 on page 166.

Note 2: When the LVD is enabled, it is recommended not to connect a pull-up resistor or capacitor. A 10nF pull-down capacitor is required to filter noise on the reset line.

Note 3: In case a capacitive power supply is used, it is recommended to connect a 1MΩ pull-down resistor to the $\overline{\text{RESET}}$ pin to discharge any residual voltage induced by the capacitive effect of the power supply (this will add 5µA to the power consumption of the MCU).

Note 4: Tips when using the LVD:

- 1. Check that all recommendations related to reset circuit have been applied (see notes above).
- 2. Check that the power supply is properly decoupled (100nF + 10µF close to the MCU). Refer to AN1709 and AN2017. If this cannot be done, it is recommended to put a 100nF + 1MΩ pull-down on the $\overline{\text{RESET}}$ pin.
- 3. The capacitors connected on the RESET pin and also the power supply are key to avoid any start-up marginality. In most cases, steps 1 and 2 above are sufficient for a robust solution. Otherwise: replace 10nF pull-down on the $\overline{\text{RESET}}$ pin with a 5µF to 20µF capacitor.

12.12 10-BIT ADC CHARACTERISTICS

Subject to general operating conditions for V_{DD}, f_{CPU}, and T_A unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{ADC}	ADC clock frequency		0.4		2	MHz
V_{AREF}	Analog reference voltage	$0.7*V_{DD} \leq V_{AREF} \leq V_{DD}$	3.8		V_{DD}	V
V_{AIN}	Conversion voltage range [1]		V_{SSA}		V_{AREF}	
I_{lkg}	Positive input leakage current for analog input	$-40°C \leq T_A \leq 85°C$ range			±250	nA
		Other T_A ranges			±1	µA
	Negative input leakage current on robust analog pins (ROM devices only)[2]	$V_{IN}<V_{SS,} \mid I_{IN} \mid < 400µA$ on adjacent robust analog pin		5	6	µA
I_{lkg}	Positive input leakage current for analog input	$-40°C \leq T_A \leq 85°C$ range			±250	nA
		Other T_A ranges			±1	µA
	Negative input leakage current on robust analog pins (ROM devices only)[2]	$V_{IN}<V_{SS,} \mid I_{IN} \mid < 400µA$ on adjacent robust analog pin		5	6	µA
R_{AIN}	External input impedance				see Figure 110 and Figure 111[2)3)4)]	kΩ
C_{AIN}	External capacitor on analog input					pF
f_{AIN}	Variation freq. of analog input signal					Hz
C_{ADC}	Internal sample and hold capacitor			12		pF
t_{ADC}	Conversion time (Sample+Hold) f_{CPU}=8MHz, SPEED=0 f_{ADC}=2MHz			7.5		µs
t_{ADC}	- No of sample capacitor loading cycles - No. of Hold conversion cycles			4 11		$1/f_{ADC}$

Notes:

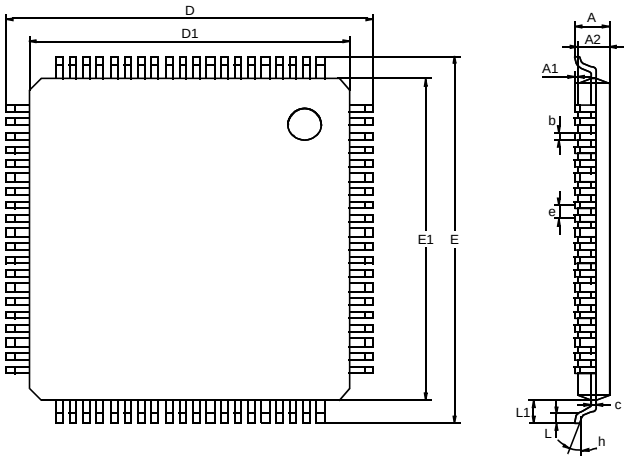
1. Any added external serial resistor will downgrade the ADC accuracy (especially for resistance greater than 10kΩ). Data based on characterization results, not tested in production.

2. For Flash devices: injecting negative current on any of the analog input pins significantly reduces the accuracy of any conversion being performed on any analog input. Analog pins of flash devices can be protected against negative injection by adding a Schottky diode (pin to ground). Injecting negative current on digital input pins degrades ADC accuracy especially if performed on a pin close to the analog input pins. Any positive injection current within the limits specified for $I_{INJ(PIN)}$ and $\Sigma I_{INJ(PIN)}$ in Section 12.8 does not affect the ADC accuracy.

13 PACKAGE CHARACTERISTICS

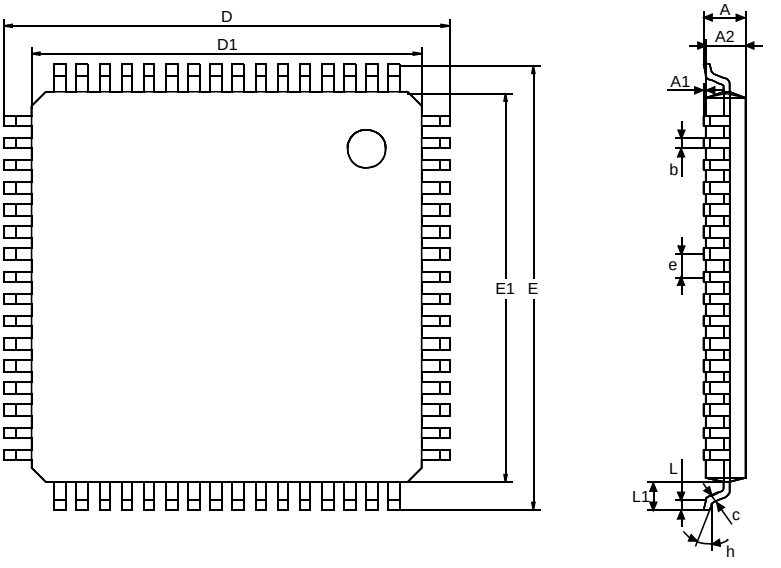
13.1 PACKAGE MECHANICAL DATA

Figure 115. 80-Pin Thin Quad Flat Package



Dim.	mm			inches		
	Min	Typ	Max	Min	Typ	Max
A			1.60			0.063
A1	0.05		0.15	0.002		0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
b	0.22	0.32	0.38	0.009	0.013	0.015
C	0.09		0.20	0.004		0.008
D		16.00			0.630	
D1		14.00			0.551	
E		16.00			0.630	
E1		14.00			0.551	
e		0.65			0.026	
θ	0°	3.5°	7°	0°	3.5°	7°
L	0.45	0.60	0.75	0.018	0.024	0.030
L1		1.00			0.039	
	Number of Pins					
N	80					

Figure 116. 64-Pin Thin Quad Flat Package



Dim.	mm			inches		
	Min	Typ	Max	Min	Typ	Max
A			1.60			0.063
A1	0.05		0.15	0.002		0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
b	0.30	0.37	0.45	0.012	0.015	0.018
c	0.09		0.20	0.004		0.008
D		16.00			0.630	
D1		14.00			0.551	
E		16.00			0.630	
E1		14.00			0.551	
e		0.80			0.031	
θ	0°	3.5°	7°	0°	3.5°	7°
L	0.45	0.60	0.75	0.018	0.024	0.030
L1		1.00			0.039	
	Number of Pins					
N	64					

13.3 SOLDERING INFORMATION

In accordance with the RoHS European directive, all STMicroelectronics packages will be converted in 2005 to lead-free technology, named ECOPACK™ (for a detailed roadmap, please refer to PCN CRP/04/744 "Lead-free Conversion Program - Compliance with RoHS", issued November 18th, 2004).

- ECOPACK™ packages are qualified according to the JEDEC STD-020B compliant soldering profile.
- Detailed information on the STMicroelectronic ECOPACK™ transition program is available on www.st.com/stonline/leadfree/, with specific technical Application notes covering the main technical aspects related to lead-free conversion (AN2033, AN2034, AN2035, AN2036).

Backward and forward compatibility:

The main difference between Pb and Pb-free soldering process is the temperature range.

– ECOPACK™ TQFP packages are fully compatible with Lead (Pb) containing soldering process (see application note AN2034)

– TQFP Pb-packages are compatible with Lead-free soldering process, nevertheless it's the customer's duty to verify that the Pb-packages maximum temperature (mentioned on the Inner box label) is compatible with their Lead-free soldering temperature.

Table 29. Soldering Compatibility (wave and reflow soldering process)

Package	Plating material devices	Pb solder paste	Pb-free solder paste
TQFP	NiPdAu (Nickel-palladium-Gold)	Yes	Yes *

* Assemblers must verify that the Pb-package maximum temperature (mentioned on the Inner box label) is compatible with their Lead-free soldering process.

DEVICE CONFIGURATION AND ORDERING INFORMATION (Cont'd)

Table 32. Suggested List of Socket Types

Device	Socket (supplied with ST7MDT20M-EMU3)	Emulator Adapter (supplied with ST7MDT20M-EMU3)
TQFP64 14 x14	CAB 3303262	CAB 3303351
TQFP64 10 x10	YAMAICHI IC149-064-*75-*5	YAMAICHI ICP-064-6
TQFP80 14 X 14	YAMAICHI IC149-080-*51-*5	YAMAICHI ICP-080-7

14.3.1 Socket and Emulator Adapter Information

For information on the type of socket that is supplied with the emulator, refer to the suggested list of sockets in Table 32.

Note: Before designing the board layout, it is recommended to check the overall dimensions of the socket as they may be greater than the dimensions of the device.

For footprint and other mechanical information about these sockets and adapters, refer to the manufacturer's datasheet (www.yamaichi.de for TQFP64 10 x 10 and TQFP80 14 x 14 and www.cabgmbh.com for TQFP64 14 x 14)

Related Documentation

AN 978: ST7 Visual Develop Software Key Debugging Features

AN 1938: ST7 Visual Develop for ST7 Cosmic C toolset users

AN 1939: ST7 Visual Develop for ST7 Metroworks C toolset users

AN 1940: ST7 Visual Develop for ST7 Assembler Linker toolset users